



Model : CBAG0021211000-01

BGA Heat Sink Specification

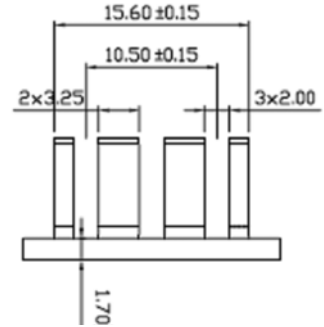
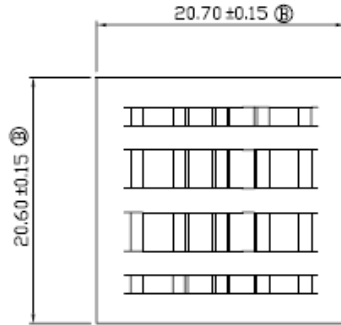
For 21x21 Chip set



1. Material: Al 6063

2. Dimension

Foot print : 21x21mm
Height : 10 mm
Base (thickness) : 1.7mm



3. Finish: Black Anodize

4. Accessory :

Clip : Plastic (UL94-V0)
Thermal pad : 8612I or others



Performance

Heat Source (LxW)	15x15
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